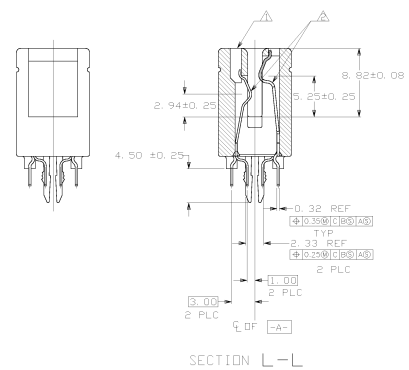
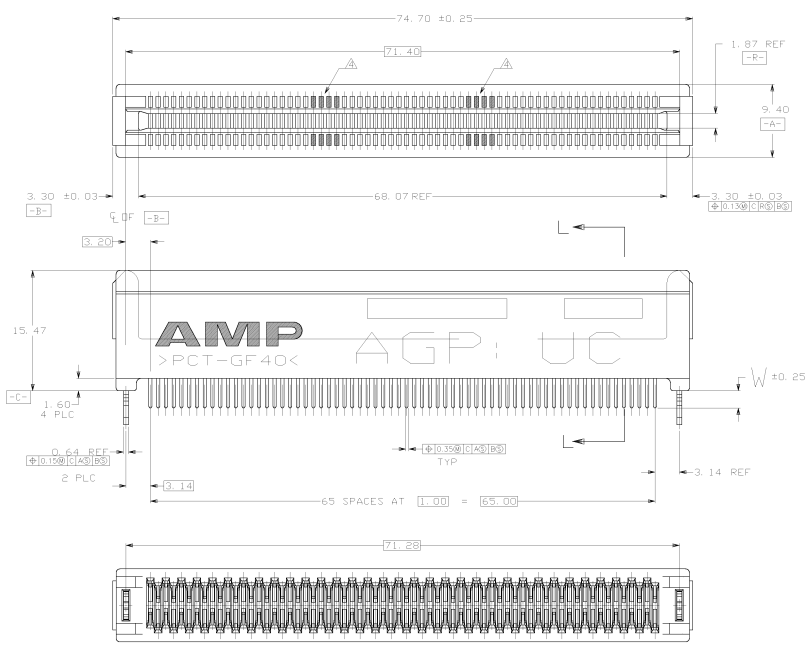
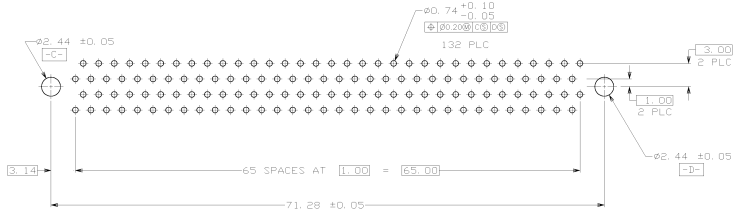


THE BOARD IS UNPLATED  
 REORDER FOR INFORMATION  
 ALL DIMENSIONS IN MILLIMETERS  
 ALL DIMENSIONS IN MILLIMETERS

REVISIONS			
REV	DATE	BY	APP
A	1998-09-01	ST	ST
B	1998-09-01	ST	ST
C	1998-09-01	ST	ST



- ▲ MATERIAL: HOUSING, THERMOPLASTIC, COLOR: BROWN.  
CONTACTS: PHOSPHOR BRONZE.  
HOLD-DOWNS, BRASS.
- ▲ FINISH: CONTACTS, 1.27 MIN. MICROMETERS NICKEL ALL OVER,  
0.38 MIN. MICROMETERS GOLD OVER NICKEL IN CONTACT AREA,  
2.54 MIN. MICROMETERS TIN OVER NICKEL ON SOLDER TAILS.
- ▲ REFER TO INTEL ACCELERATED GRAPHICS PORT INTERFACE SPECIFICATION  
FOR RECOMMENDED MATING PAD PATTERNS FOR AGP 1X, 2X AND 4X BOARDS.
- ▲ SHADDED CONTACT LOCATIONS ARE AT RISK OF DAMAGE DURING MATING AND  
UNMATING WITH AGP-1X AND AGP-2X/4X CIRCUITS.
- ▲ FINISH: CONTACTS, 1.27 MIN. MICROMETERS NICKEL ALL OVER,  
0.0254-0.0762 MICROMETERS GOLD OVER NICKEL IN CONTACT AREA,  
2.54 MIN. MICROMETERS TIN OVER NICKEL ON SOLDER TAILS.
- ▲ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/SINISI



RECOMMENDED CONNECTOR MOUNTING HOLE PATTERN  
 (CONNECTOR SIDE SHOWN)

REV	DATE	BY	APP	DESCRIPTION
1	3-18	ST	ST	5145376-1
2	5-4	ST	ST	5145376-2
3	3-18	ST	ST	5145376-3
4	2-54	ST	ST	5145376-4
5	2-16	ST	ST	5145376-5

THIS DRAWING IS A CONTROLLED DOCUMENT				YAO Electronics Corporation	
REV	DATE	BY	APP	REV	DATE
1	3-18	ST	ST	1	3-18
2	5-4	ST	ST	2	5-4
3	3-18	ST	ST	3	3-18
4	2-54	ST	ST	4	2-54
5	2-16	ST	ST	5	2-16